

G3380N

Non-silicone Thermal Interface Grease

LiPOLY G3380N has made by non-silicon resin material, which is low-molecular-weight siloxanes with non-volatile, with low thermal resistance, great thermal conductive, which has been extensively use on Consumer electronics and Microprocessor for their thermal control techniques. The thermal interface grease can cover several coat on the component interface, when the component's temperature raise, thermal interface grease stickiness will decrease, which can moisten the interface of components.



Features-

- Thermal conductivity: 1.3 / 3.2 / 4.5 W/m*K
- No low MW siloxane
- Low thermal impedance

Typical Applications-

- CPU and chip coolers
- Switching power supplies
- LED appliance
- Between any heat-generating component and heat sink

Specifications-

- Storage temp : RT25°C
- Stock shelf Life : 12 months from date of shipment

PROPERTY	G3380NA	G3380NB	G3380NC	TEST METHOD	UNIT
Color	White	Gray	Gray	Visual	-
Resin Base	Non-Silicone	Non-Silicone	Non-Silicone	-	-
Filler	Non-metal	metal	metal	-	-
Viscosity	96	43	93	ASTM D2196	PaS
Density	2.2	1.9	2.1	ASTM D792	g/cm ³
Application temperature	-60~150	-60~150	-60~150	-	°C
Bond Line Thickness	55	33	72	-	µm
ELECTRICA					
Dielectric breakdown	350	N/A	N/A	ASTM D149	V/mil
Surface resistivity	>10 ¹¹	N/A	N/A	ASTM D257	Ohm
Volume resistivity	>10 ¹¹	N/A	N/A	ASTM D257	Ohm-m
THERMAL					
Thermal Conductivity	1.3	3.2	4.5	ASTM D5470	W/m*K
Thermal impedance@50 psi	0.05	0.035	0.02	ASTM D5470	°C-in ² /W
Thermal impedance@50 psi	32.2	22.5	12.9	ASTM D5470	°C-mm ² /W

※ These data are provided for reference only. Engineers are reminded to test the material in varied application.